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FAN54300 — USB-Compliant, Dual-Power Input, Single-Cell, Li-Ion Switching Charger with USB-OTG Boost Regulator

Features

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-Ion and Li-Polymer Battery Packs
- Accepts USB or Dedicated Power Input Source
- 5 V, 300 mA Boost Mode for USB OTG from 2.5 to 4.5 V Battery Input
- Charge Voltage Accuracy: $\pm 0.5\%$ at $T_A = 25^\circ\text{C}$
 $\pm 1\%$ from $T_A = 0$ to 125°C
- $\pm 5\%$ USB Input Current Regulation Accuracy
- $\pm 5\%$ Charge Current Regulation Accuracy
- 20 V Absolute Maximum Input Voltage
- 9.5 V Maximum Input Operating Voltage on VIN Pin, 6.5 V Maximum on VBUS Pin
- Up to 1.5 A Maximum Charge Rate
- Programmable Charge and Mode through High-Speed I²C Interface (3.4 Mb/s) with Fast Mode Plus Compatibility
 - Input Current
 - Fast-Charge / Termination Current
 - Charger Voltage
 - Safety Timer
 - Termination Enable
- 3 MHz Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint, 1 μH , External Inductors
- Safety Timer with Reset Control
- Weak Input Sources Accommodated by Reducing Charging Current to Maintain Minimum V_{BUS} Voltage
- Low Reverse Leakage from Battery Drain to VBUS or VIN
- Programmable LED Drive for Charge Indication
- Register and Slave Addresses Compatible with FAN540X and FAN542X Families

Description

The FAN54300 combines two highly integrated switch-mode chargers and a boost regulator to minimize single-cell Li-Ion charging time from a USB and/or auxiliary power source.

Charging parameters and operating modes are programmable through an I²C Bus® interface that operates up to 3.4 Mbps. The charger and boost regulator circuits switch at 3 MHz to minimize the size of the external passive components.

The FAN54300 provides battery charging in three phases: conditioning, constant current, and constant voltage.

To ensure USB compliance and minimize charging time, the USB input current is limited to the value set through the I²C host. Charge termination is determined by a programmable minimum current level. A safety timer with reset control provides a safety backup for the I²C host.

The IC automatically restarts the charge cycle when the battery falls below an internal threshold. If the input source is removed, the IC enters a high-impedance mode, with leakage from the battery to the input prevented. Charge status is reported back to the host through the I²C port. Charge current is reduced when the die temperature reaches 120°C .

The FAN54300 can operate as a boost regulator on command from the system. The boost regulator includes a soft-start that limits inrush current from the battery.

The FAN54300 is available in a 30-bump, 0.4 mm pitch, wafer-level, chip-scale package (WLCSP).

Applications

- Cell Phones, Smart Phones, PDAs
- Digital Cameras
- Portable Media Players

Ordering Information

Part Number	Temperature Range	Package	Packing
FAN54300UCX	-40 to 85°C	30-Ball, WLCSP, 5x6 Array, 0.4mm Pitch, 586 μm Package Height	Tape and Reel

Table 1. Feature Summary

Part Number	Automatic Charge	Battery Absent Charge
FAN54300	Yes	No

Typical Application

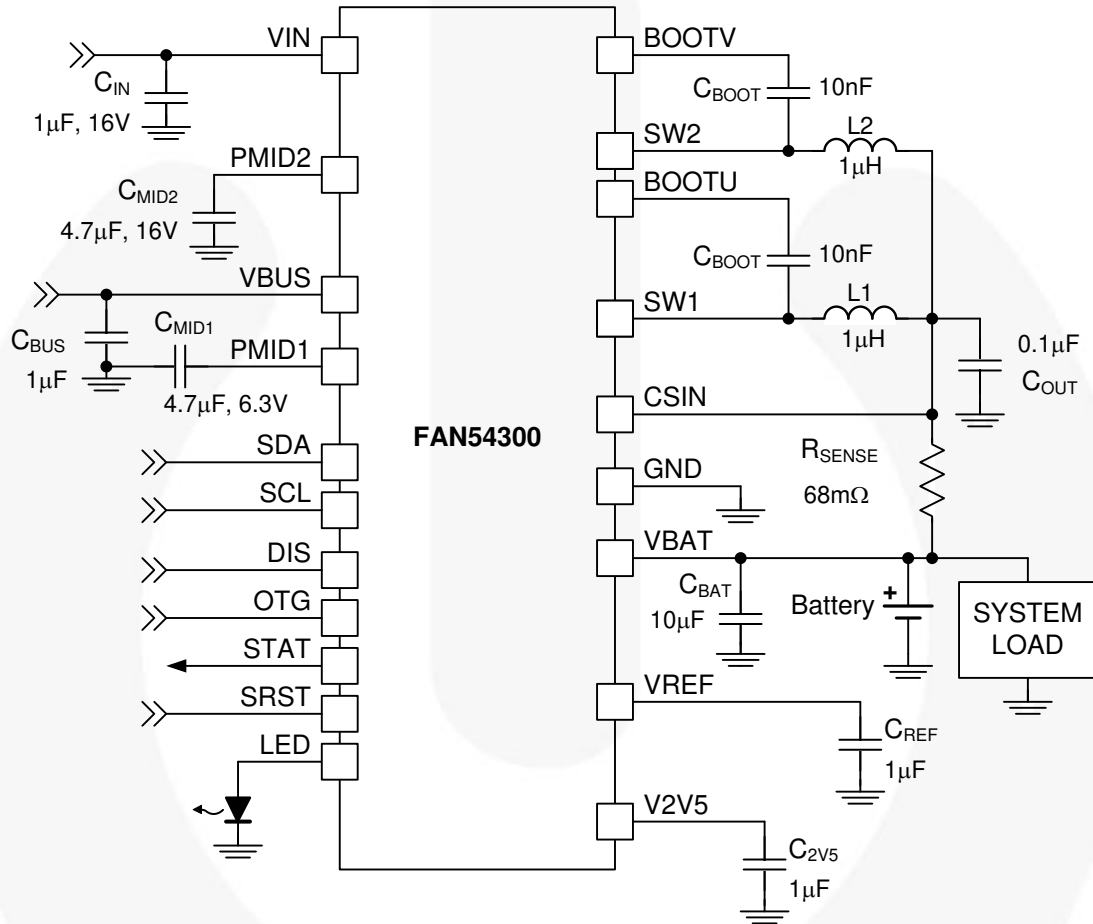


Figure 1. Typical Application

Block Diagrams

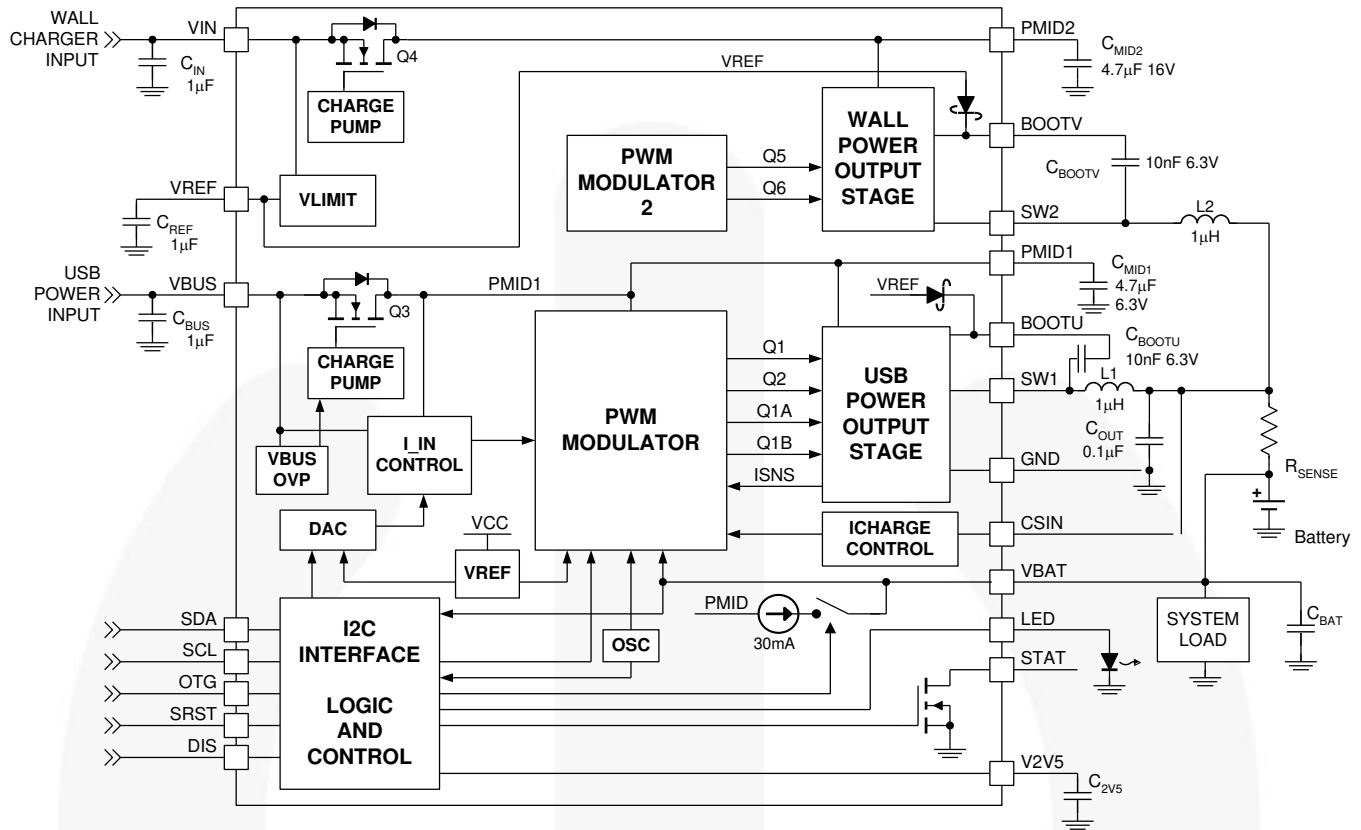


Figure 2. IC and System Block Diagram

Table 2. Recommended External Components

Component	Description	Vendor	Parameter	Typ.	Units
L1, L2:	Charge Currents to 1 A: 1 μ H, 20%, 1.3 A, 2016	Murata: LQM2MPN1R0M	L	1.0	μ H
			DCR	85	m Ω
	Charge Currents Above 1 A: 1 μ H, 20%, 1.6 A, 2520	Murata: LQM2HPN1R0M	L	1.0	μ H
			DCR	55	m Ω
C _{BAT}	10 μ F, 20%, 6.3 V, X5R, 0603	Murata: GRM188R60J106M	C	10	μ F
C _{MID1,2}	4.7 μ F, 10%, 16 V, X5R, 0805	Murata: GRM21BR61C475K	C	4.7	μ F
C _{IN} , C _{BUS}	1.0 μ F, 10%, 16 V, X5R, 0603	Murata: GRM188R61E105K	C	1.0	μ F
C _{BOOT}	10 nF, 10%, 6.3 V, X5R, 0201	Murata: GRM033R70J103K	C	10	nF
C _{OUT}	0.1 μ F, 10%, 6.3 V, X5R, 0201	Murata: GRM033R60J104K	C	0.1	μ F
C _{2V5} , C _{REF}	1 μ F, 10%, 6.3 V, X5R, 0402	Murata: GRM155R60J105M	C	1.0	μ F



Pin Configuration

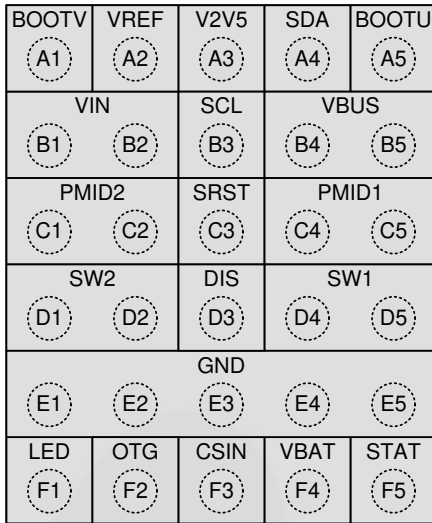


Figure 4. Pin Assignments (Top View)

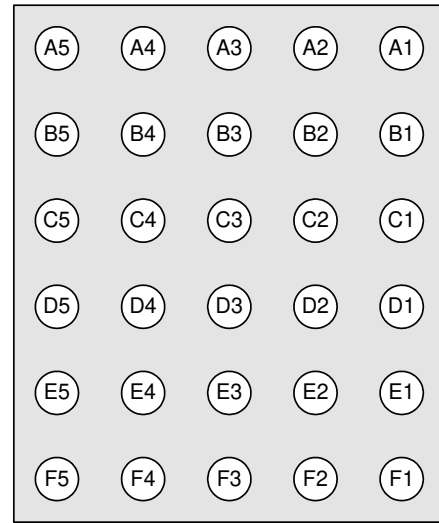


Figure 5. Pin Assignments (Bottom View)

Pin Definitions

Pin #	Name	Description
A1	BOOTV	BOOT. High-side NMOS driver supply. Connect a 10nF capacitor from SW2 to this pin.
A2	VREF	Bias Regulator Output. Connect to a 1 μ F capacitor to PGND. This pin supplies the internal gate drive and power supply to the IC while charging. Up to 5 mA of current can be provided from this pin to drive external circuits. This pin is active when either V_{IN} or V_{BUS} are above V_{BAT} .
A3	V2V5	2.5 V Regulator. Connect to a 1 μ F capacitor to PGND. Up to 5 mA can be provided from this pin to drive external circuits. This regulator is powered only when VIN is connected.
A4	SDA	I²C Interface Serial Data. This pin should not be left floating.
A5	BOOTU	BOOT. High-side NMOS driver supply. Connect a 10 nF capacitor from SW1 to this pin.
B1, B2	VIN	Charger Input Voltage. Bypass with a minimum of 1 μ F, 16 V capacitor to GND.
B3	SCL	I²C Interface Serial Clock. This pin should not be left floating.
B4, B5	VBUS	USB Input Voltage. Bypass with a 1 μ F, 16 V capacitor to GND.
C1, C2	PMID2	Power Input Voltage for VIN Power Source. Power input to the charger regulator, bypass point for the VIN input current sense, and high-voltage input switch. Bypass with a minimum of 4.7 μ F, 16 V capacitor to PGND.
C3	SRST	Safety Reset. When LOW, both safety registers are reset to their default values. When HIGH, the safety registers reset when V_{BAT} drops below V_{SHORT} .
C4, C5	PMID1	Power Input Voltage for VBUS Power Source. Power input to the VBUS switching charger regulator, bypass point for the VBUS input current sense, and high-voltage input switch. Bypass with a minimum of 4.7 μ F, 6.3 V capacitor to PGND.
D1, D2	SW2	Switching Node for VIN Charger. Connect to the output inductor.
D3	DIS	Charge Disable. When this pin is HIGH, charging is disabled and no timers are reset. When LOW, charging is controlled by the I ² C registers. This pin does not affect the 32-second timer.
D4, D5	SW1	Switching Node for VBUS Charger and OTG Boost. Connect to the output inductor.
E1–E5	GND	Ground. Power return for gate drive and power transistors as well as IC signal ground. The connection from this pin to the bottoms of the C_{PMID} capacitors should be as short as possible.
F1	LED	Light Emitting Diode Output. Up to 5 mA current source drive from the active PMID indicates the battery is charging.

Pin #	Name	Description
F2	OTG	On The Go. When unattended charging is indicated, the level on this pin sets the I_{BUS} current limit. This pin is also used to put the IC into Boost Mode.
F3	CSIN	Current-Sense Input. Connect to sense resistor in series with the battery. The IC uses this node to sense current into the battery. Bypass this pin with a 0.1 μ F capacitor to PGND.
F4	VBAT	Battery Voltage. Connect to the positive (+) terminal of the battery pack. Bypass with a 10 μ F capacitor to PGND.
F5	STAT	Status. Open-drain output indicating charge status. The IC pulls this pin LOW when charging is in process.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V _{BUS}	VBUS Voltage	Continuous	−1.4	20.0	V
		Pulsed, 100 ms Maximum Non-Repetitive	−2.0		
V _{IN}	VIN Voltage		−2.0	20.0	V
V _{BOOTU}	BOOTU Voltage		−0.7	20.0	V
V _{BOOTV}	BOOTV Voltage		−0.7	20.0	V
V _{PMID1}	PMID1 Voltage		−1.0	20.0	V
V _{SW1}	SW1 Voltage		−0.7	6.5	V
V _{PMID2}	PMID2 Voltage		−1.0	20.0	V
V _{SW2}	SW2 Voltage		−0.7	12.0	V
V _O	Other Pins		−0.3	6.5 ⁽¹⁾	V
$\frac{dV_{BUS}}{dt}$	Maximum Rate of V _{BUS} Increase Above 5.5 V when IC Enabled			4	V/μs
$\frac{dV_{IN}}{dt}$	Maximum Rate of V _{IN} Increase Above 9.5 V when IC Enabled			4	V/μs
ESD	Electrostatic Discharge Protection Level	Human Body Model per JESD22-A114	2.0		kV
		Charged Device Model per JESD22-C101	1.5		kV
T _J	Junction Temperature		−40	+150	°C
T _{STG}	Storage Temperature		−65	+150	°C
T _L	Lead Soldering Temperature, 10 Seconds			+260	°C

Note:

1. Lesser of 6.5 V or V_{REF} + 0.3 V.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Units
V _{BUS}	VBUS Supply Voltage	4	6	V
V _{IN}	VIN Supply Voltage	4.0	9.5	V
T _A	Ambient Temperature	−30	+85	°C
T _J	Junction Temperature	0	+125	°C

Thermal Properties

Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature T_{J(max)} at a given ambient temperature T_A.

Symbol	Parameter	Typical	Unit
θ _{JA}	Junction-to-Ambient Thermal Resistance	60	°C/W
θ _{JB}	Junction-to-PCB Thermal Resistance	20	°C/W

Electrical Specifications

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for T_J and T_A , V_{BUS} or $V_{IN} = 5.0\text{ V}$, $HZ1$, $HZ2$, $OPA_MODE = 0$, (Charger Mode). SCL , SDA , $OTG = 0$ or 1.8 V . Typical values are for $T_J = 25^\circ\text{C}$.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Power Supplies						
I _{VBUS}	VBUS Current	PWM Switching, Open Battery, TE=0		33		mA
		PWM Not Switching (V _{BAT} > V _{OREG})		3.6		mA
		0°C < T _J < 85°C, HZ1 = 1, V _{BAT} > V _{LOWV}		350	500	μA
		0°C < T _J < 85°C, HZ1 = 1, V _{BAT} < V _{LOWV} , 32S Mode		350	500	μA
I _{VIN}	VIN Current	PWM Switching, Open Battery, TE=0		33		mA
		PWM Not Switching (V _{BAT} >V _{OREG})		2.6		mA
		0°C < T _J < 85°C, HZ2 = 1, V _{IN} > V _{LOWV}		350	500	μA
		0°C < T _J < 85°C, HZ2 = 1, V _{IN} < V _{LOWV} , 32S Mode		350	500	μA
I _{BAT}	Battery Discharge Current in High-Z Mode	0°C < T _J < 85°C, HZ1=HZ2 = 1 or DIS=1, V _{BAT} = 4.2 V			20	μA
		0°C < T _J < 85°C, V _{BAT} = 4.2 V, V _{IN} = V _{BUS} = Open or GND, HZ1=HZ2=1, SDA = SCL = 1.8 V, No I ² C Traffic			30	μA
Charger Voltage Regulation						
V _{OREG}	Charge Voltage Range		3.5		4.4	V
	Charge Voltage Accuracy	T _A = 25°C	−0.5		+0.5	%
		T _J = 0 to 125°C	−1		+1	%
Charging Current Regulation						
I _{OCHRG}	Output Charge Current Range	V _{LOWV} < V _{BAT} < V _{OREG} , V _{BUS} > V _{SLP} , R _{SENSE} = 68 mΩ	550		1500	mA
	Charge Current Accuracy Across R _{SENSE}	20 mV ≤ V _{I_{REG}} ≤ 40 mV	92	97	102	% of Setting
		V _{I_{REG}} > 40 mV	94	97	100	
Weak-Battery Detection						
V _{LOWV}	Weak-Battery Threshold Accuracy	3.4 ≤ V _{LOWV} ≤ 3.7	-5		+5	%
	Weak Battery Deglitch Time	Rising Voltage, 2 mV Overdrive		30		ms
Logic Levels: DIS, SDA, SCL, OTG						
V _{I_H}	HIGH-Level Input Voltage		1.05			V
V _{I_L}	LOW-Level Input Voltage				0.4	V
I _{IN}	Input Bias Current	Input Tied to GND or V _{BAT}		0.01	1.00	μA
Charge Termination Detection						
I _(TERM)	Termination Current Range	V _{BAT} > V _{OREG} − V _{RCH} , V _{BUS} > V _{SLP} , R _{SENSE} = 68 mΩ	50		400	mA
	Termination Current Accuracy	[V _{CSIN} − V _{BAT}] from 3 mV to 20 mV	−25%		+25%	
		[V _{CSIN} − V _{BAT}] from 20 mV to 40 mV	−5%		+5%	
	Termination Current Deglitch Time	2 mV Overdrive		30		ms

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Electrical Specifications (Continued)

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for T_J and T_A , V_{BUS} or V_{IN} = 5.0 V, HZ1, HZ2, OPA_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8V. Typical values are for T_J = 25°C.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
VBUS Input Power Source Detection						
V _{BUS(MIN)1}	V _{BUS} Input Voltage Rising	To Start V _{BUS} Validation	4.20	4.30	4.40	V
V _{BUS(MIN)2}	Min. V _{BUS} to Pass Validation	During V _{BUS} Validation Period	4.00	4.08	4.15	V
V _{BUS(MIN)3}	Min. V _{BUS} During Charge	During Charging	3.64	3.71	3.78	V
t _{VBUS_VALID}	V _{BUS} Validation Time			30		ms
VBUS _{LOAD}	V _{BUS} Load	V _{BUS} = 5 V, Applied at V _{BUS} Validation		50		mA
VIN Input Power Source Detection						
V _{IN(MIN)1}	V _{IN} Input Voltage Rising	To Start V _{IN} Validation	4.20	4.30	4.40	V
V _{IN(MIN)2}	Min. V _{IN} to Pass Validation	During V _{IN} Validation Period	4.00	4.08	4.15	V
V _{IN(MIN)3}	Min. V _{IN} During Charge	During Charging	3.64	3.71	3.78	V
t _{VBUS_VALID}	V _{IN} Validation Time			30		ms
V _{INLOAD}	V _{IN} Load	V _{IN} = 5 V, Applied at V _{IN} Validation		50		mA
Input Current Limit						
I _{BUSLIM}	VBUS Input Current-Limit Threshold	I _{BUS} set to 100 mA	88	93	98	mA
		I _{BUS} set to 500 mA	450	475	500	
V _{2V5} 2.5V Linear Regulator						
V _{2V5}	2.5 V Regulator Output	I _{2V5} from 0 to 5 mA, V _{IN} > 4.75 V	2.35	2.50	2.65	V
	Current Limit		6	8		mA
V _{REF} Bias Generator						
V _{REF}	Bias regulator voltage	V _{IN} > V _{IN(MIN)}	3.5		6.0	V
	current limit		10	15		mA
Battery Recharge Threshold						
V _{RCH}	Recharge Threshold	Below V _(OREG)	100	120	150	mV
	Deglitch Time	VBAT falling below V _{RCH} threshold		130		ms
STAT Output						
V _{STAT(OL)}	STAT Output LOW	I _{STAT} = 10 mA			0.4	V
I _{STAT(OH)}	STAT High Leakage Current	V _{STAT} = 5 V			1	μA
LED Output						
I _{LED(ON)}	LED Output Current Accuracy	V _{LED} from 1.5 to 3.5 V, Max. (V _{REF} , V _{BAT}) – V _{LED} > 100 mV	–30		+30	%
I _{LED(OFF)}	LED Off-State Leakage Current	V _{LED} = 0 V			1	μA
Battery Detection						
I _{DETECT}	Battery Detection Current Before Charge Complete (Sink Current) ⁽²⁾	Begins After Termination Detected and V _{BAT} ≤ V _{OREG} – V _{RCH}		–0.45		mA
t _{DETECT}	Battery Detection time			262		ms

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Electrical Specifications (Continued)

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for T_J and T_A , V_{BUS} or $V_{IN} = 5.0\text{ V}$, $HZ1$, $HZ2$, $OPA_MODE = 0$, (Charger Mode). SCL , SDA , $OTG = 0$ or 1.8 V . Typical values are for $T_J = 25^\circ\text{C}$.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Sleep Comparator						
V _{SLP}	Sleep Mode Entry Threshold, V _{BUS} – V _{BAT} or V _{IN} – V _{BAT}	2.3 V ≤ V _{BAT} ≤ V _{OREG} , V _{PWRIN} Falling	0	90	160	mV
V _{SLP_EXIT}	Sleep Mode Exit Hysteresis	2.3 V ≤ V _{BAT} ≤ V _{OREG}		40		mV
	Deglitch Time for V _{BUS} Rising Above V _{SLP} + V _{SLP_EXIT}	Rising Voltage		30		ms
Power Switches (see Figure 3)						
R _{DS(ON)}	Q3 On Resistance (VBUS to PMID1)	IBUS(LIMIT) ≥ 500 mA		210	300	mΩ
	Q1 On Resistance (PMID1 to SW1)			110	225	
	Q2 On Resistance (SW1 to GND)			130	225	
	Q4 On Resistance (VIN to PMID2)			160	225	
	Q5 On Resistance (PMID2 to SW2)			110	225	
	Q6 On Resistance (SW2 to GND)			190	350	
Charger PWM Modulator						
f _{SW}	Oscillator Frequency		2.7	3.0	3.3	MHz
D _{MAX}	Maximum Duty Cycle				100	%
D _{MIN}	Minimum Duty Cycle			0		%
I _{SYNC}	Synchronous to Non-Synchronous Current Threshold ⁽³⁾	Low-Side MOSFET Cycle-by-Cycle Current Limit		-120		mA
Boost Mode Operation (OPA_MODE = 1, HZ1 = 0)						
V _{BOOST}	Boost Output Voltage at VBUS	2.5 V < V _{BAT} < 4.5 V, 0-200 mA Load	4.80	5.05	5.17	V
		2.7 V < V _{BAT} < 4.5 V, 0-300 mA Load	4.77	5.05	5.17	
I _{BAT(BOOST)}	Boost Mode Quiescent Current	PFM Mode, V _{IN} = 3.6 V, I _{OUT} = 0		300	400	μA
I _{LIMPK(BST)}	Q2-Peak Current Limit		1160	1380	1550	mA
V _{BAT(MAX)}	Maximum Battery Input for Boost Operation	V _{BAT} Rising	4.7			V
	Hysteresis	V _{BAT} Falling		125		mV
UVLO _{BST}	Minimum Battery Voltage for Boost Operation	While Boost Active		2.42		V
		To Start Boost Regulator		2.58	2.70	
VBUS, VIN Load Resistance						
R _{VBUS}	VBUS to GND Resistance	Normal Operation	500	1000	1500	Ω
		V _{BUS} Validation	50	110	175	Ω
R _{VIN}	VIN to GND Resistance	Normal Operation	500	1000	1500	Ω
		V _{IN} Validation	50	110	175	Ω

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Electrical Specifications (Continued)

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for T_J and T_A , V_{BUS} or V_{IN} = 5.0 V, HZ1, HZ2, OPA_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8 V. Typical values are for T_J = 25°C.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Protection and Timers						
VBUS _{OV} P	VBUS Over-Voltage Shutdown	V_{BUS} Rising	6.12	6.31	6.50	V
	Hysteresis	V_{BUS} Falling		100		mV
VIN _{OV} P	VIN Over-Voltage Shutdown	V_{IN} Rising	9.5	10.0	10.5	V
	Hysteresis	V_{IN} Falling		100		mV
V _{SHORT}	Battery Short-Circuit Threshold	V_{BAT} Rising	2.00	2.05	2.10	V
	Hysteresis	V_{BAT} Falling		100		
I _{SHORT}	Short-Circuit Current	$V_{BAT} < V_{SHORT}$	30	40	50	mA
T _{SHUTDWN}	Thermal Shutdown Threshold ⁽⁴⁾	T_J Rising		165		°C
	Hysteresis ⁽⁴⁾	T_J Falling		10		
T _{CF}	Thermal Regulation Threshold ⁽⁴⁾	Charge Current Reduction Begins		120		°C
t _{INT}	Detection Interval			2.1		s
t _{32SEC}	32-Second Timer ⁽⁵⁾	32-Second Mode	21.0		31.5	s
t _{15MIN}	15-Minute Timer	15-Minute Mode	12.0	13.5	15.0	min
Δt _{LF}	Low Frequency Timer Accuracy	Charger Inactive	-25		25	%

Notes:

- Refers to negative inductor current. At lower battery charging current, of about 20 mA, non-synchronous switching operation commences.
- Q2 and Q6 always turn on for »60 ns and then turn off if the current is below I_{SYNC}.
- Guaranteed by design.
- This tolerance applies to all timers on the IC, including soft-start and deglitching timers.

I²C Timing Specifications

Guaranteed by design.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f _{SCL}	SCL Clock Frequency	Standard Mode			100	kHz
		Fast Mode			400	
		High-Speed Mode, C _B ≤ 100 pF			3400	
		High-Speed Mode, C _B ≤ 400 pF			1700	
t _{BUF}	Bus-Free Time between STOP and START Conditions	Standard Mode		4.7		μs
		Fast Mode		1.3		
t _{HD;STA}	START or Repeated START Hold Time	Standard Mode		4		μs
		Fast Mode		600		ns
		High-Speed Mode		160		ns
t _{LOW}	SCL LOW Period	Standard Mode		4.7		μs
		Fast Mode		1.3		μs
		High-Speed Mode, C _B ≤ 100 pF		160		ns
		High-Speed Mode, C _B ≤ 400 pF		320		ns
t _{HIGH}	SCL HIGH Period	Standard Mode		4		μs
		Fast Mode		600		ns
		High-Speed Mode, C _B ≤ 100 pF		60		ns
		High-Speed Mode, C _B ≤ 400 pF		120		ns
t _{SU;STA}	Repeated START Setup Time	Standard Mode		4.7		μs
		Fast Mode		600		ns
		High-Speed Mode		160		ns
t _{SU;DAT}	Data Setup Time	Standard Mode		250		ns
		Fast Mode		100		
		High-Speed Mode		10		
t _{HD;DAT}	Data Hold Time	Standard Mode	0		3.45	μs
		Fast Mode	0		900	ns
		High-Speed Mode, C _B ≤ 100 pF	0		70	ns
		High-Speed Mode, C _B ≤ 400 pF	0		150	ns
t _{RCL}	SCL Rise Time	Standard Mode	20+0.1C _B		1000	ns
		Fast Mode	20+0.1C _B		300	
		High-Speed Mode, C _B ≤ 100 pF		10	80	
		High-Speed Mode, C _B ≤ 400 pF		20	160	
t _{FCL}	SCL Fall Time	Standard Mode	20+0.1C _B		300	ns
		Fast Mode	20+0.1C _B		300	
		High-Speed Mode, C _B ≤ 100 pF		10	40	
		High-Speed Mode, C _B ≤ 400 pF		20	80	
t _{RDA} t _{RCL1}	SDA Rise Time Rise Time of SCL after a Repeated START Condition and after ACK Bit	Standard Mode	20+0.1C _B		1000	ns
		Fast Mode	20+0.1C _B		300	
		High-Speed Mode, C _B ≤ 100 pF		10	80	
		High-Speed Mode, C _B ≤ 400 pF		20	160	

Continued on the following page...

I²C Timing Specifications

Guaranteed by design.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
t_{FDA}	SDA Fall Time	Standard Mode		$20+0.1C_B$	300	ns
		Fast Mode		$20+0.1C_B$	300	
		High-Speed Mode, $C_B \leq 100$ pF		10	80	
		High-Speed Mode, $C_B \leq 400$ pF		20	160	
$t_{SU;STO}$	Stop Condition Setup Time	Standard Mode		4		μ s
		Fast Mode		600		ns
		High-Speed Mode		160		ns
C_B	Capacitive Load for SDA, SCL				400	pF

Timing Diagrams

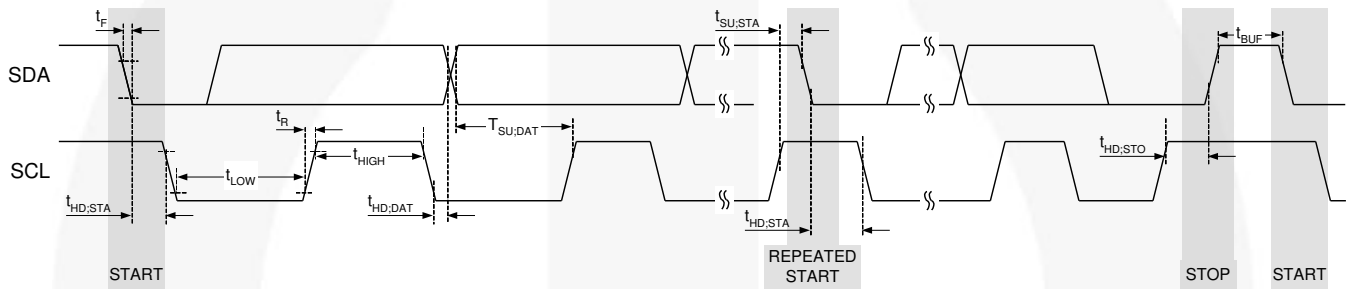
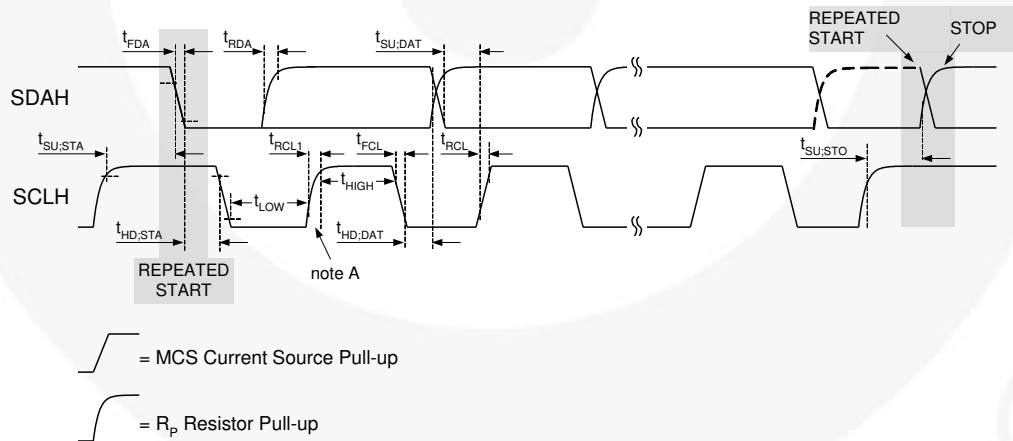


Figure 6. I²C Interface Timing for Fast and Slow Modes



Note A: First rising edge of SCLH after Repeated Start and after each ACK bit.

Figure 7. I²C Interface Timing for High-Speed Mode

VBUS Charge Mode Typical Characteristics

Unless otherwise specified, circuit of Figure 1, $V_{OREG}=4.2\text{ V}$, $V_{BUS}=5.0\text{ V}$, and $T_A=25^\circ\text{C}$.

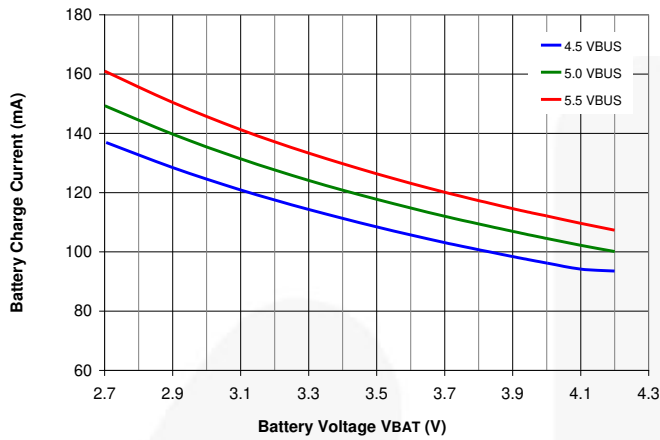


Figure 8. Battery Charge Current vs. V_{BUS} with $I_{INLIM}=100\text{ mA}$

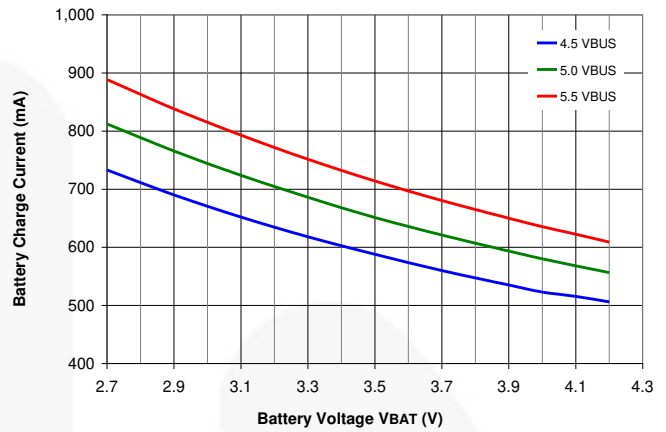


Figure 9. Battery Charge Current vs. V_{BUS} with $I_{INLIM}=500\text{ mA}$

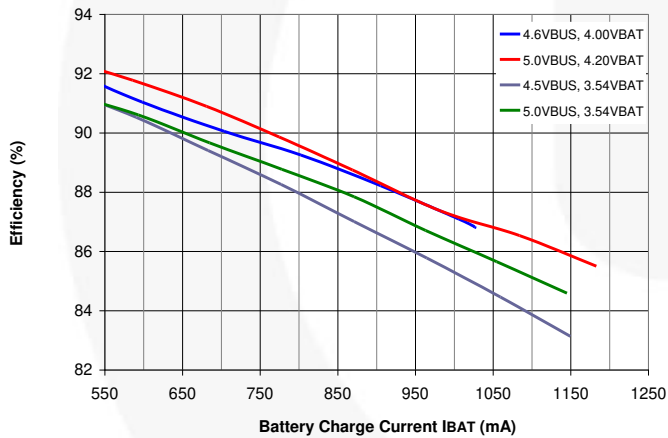


Figure 10. Charger Efficiency, No I_{INLIM} , $I_{CHARGE}=1250\text{ mA}$

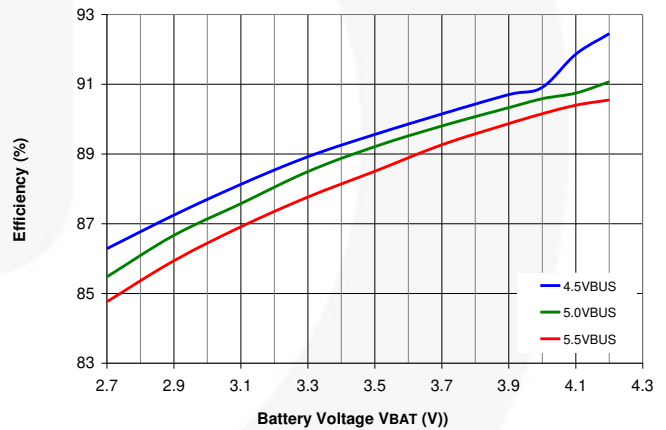


Figure 11. Charger Efficiency vs. V_{BUS} , $I_{INLIM}=500\text{ mA}$

VBUS Charge Mode Typical Characteristics

Unless otherwise specified, circuit of Figure 1, $V_{OREG}=4.2\text{ V}$, $V_{BUS}=5.0\text{ V}$, and $T_A=25^\circ\text{C}$.

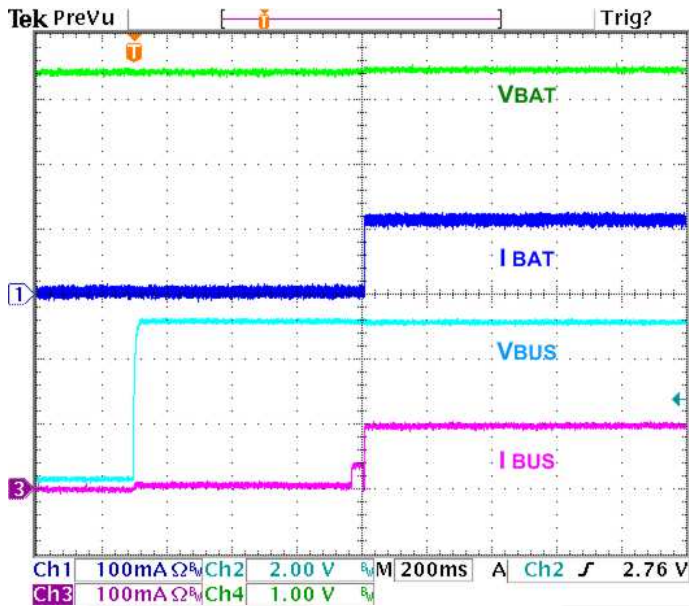


Figure 12. Auto-Charge Startup at V_{BUS} Plug-in, $I_{NLIM}=100\text{ mA}$, $OTG=1$, $V_{BAT}=3.4\text{ V}$

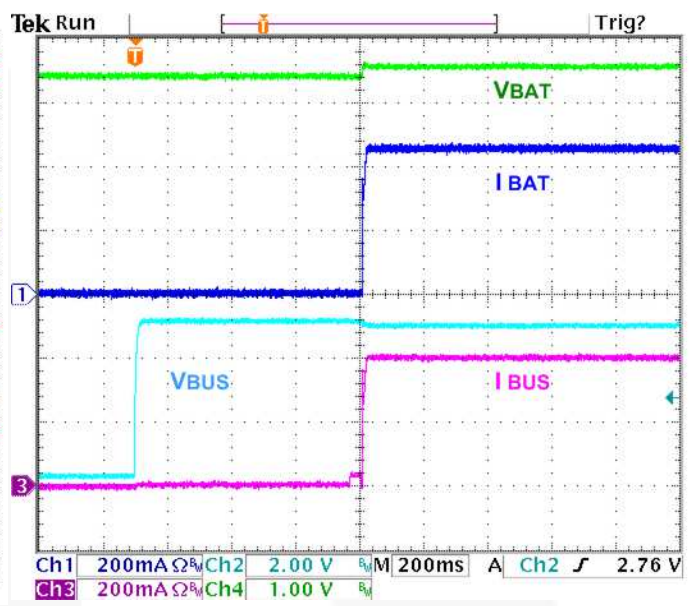


Figure 13. Auto-Charge Startup at V_{BUS} Plug-in, $I_{NLIM}=500\text{ mA}$, $OTG=1$, $V_{BAT}=3.4\text{ V}$

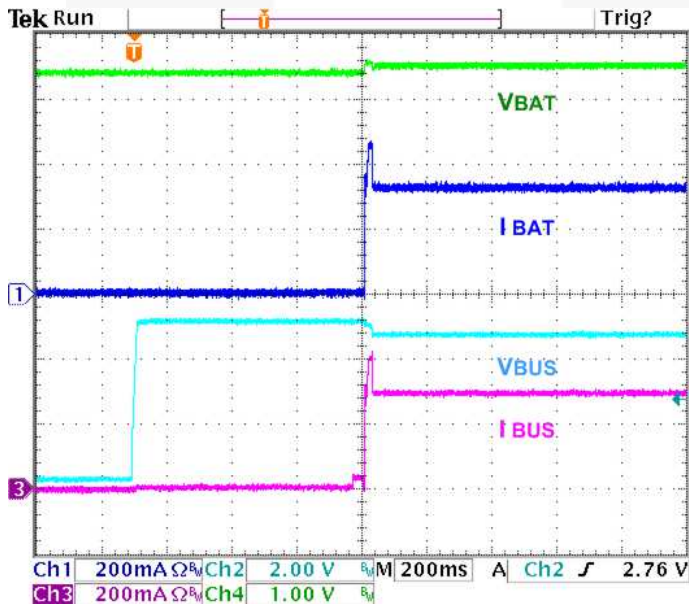


Figure 14. AutoCharge Startup with 300 mA Limited Charger / Adaptor, $I_{NLIM}=500\text{ mA}$, $OTG=1$, $V_{BAT}=3.4\text{ V}$

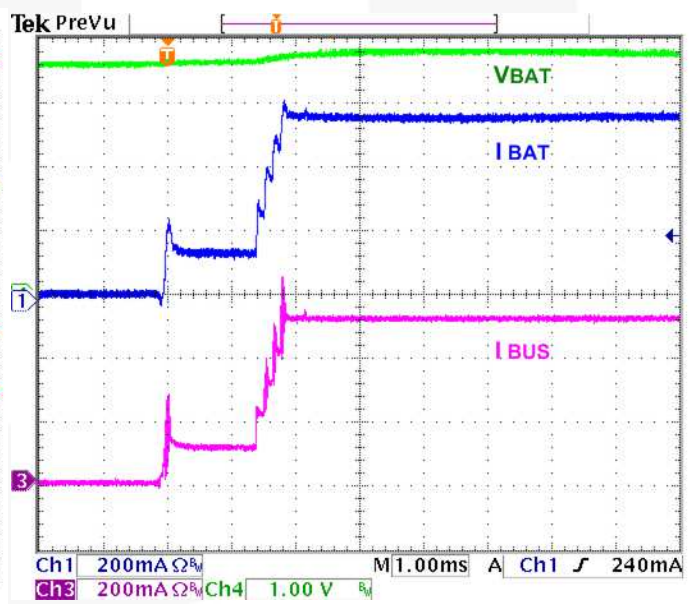


Figure 15. Charger Startup with HZ_MODE Bit Reset, $I_{NLIM}=500\text{ mA}$, $I_{CHARGE}=950\text{ mA}$, $V_{OREG}=4.2\text{ V}$, $V_{BAT}=3.6\text{ V}$

VBUS Charge Mode Typical Characteristics

Unless otherwise specified, circuit of Figure 1, $V_{OREG}=4.2\text{ V}$, $V_{BUS}=5.0\text{ V}$, and $T_A=25^\circ\text{C}$.

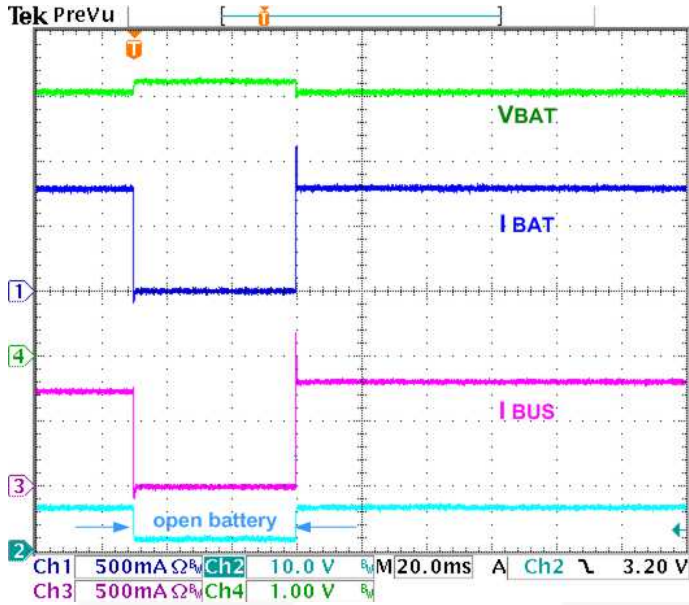


Figure 16. Battery Removal / Insertion during Charging, $V_{BAT}=3.9\text{ V}$, $I_{OCHARGE}=950\text{ mA}$, No I_{INLIM} , $TE=0$

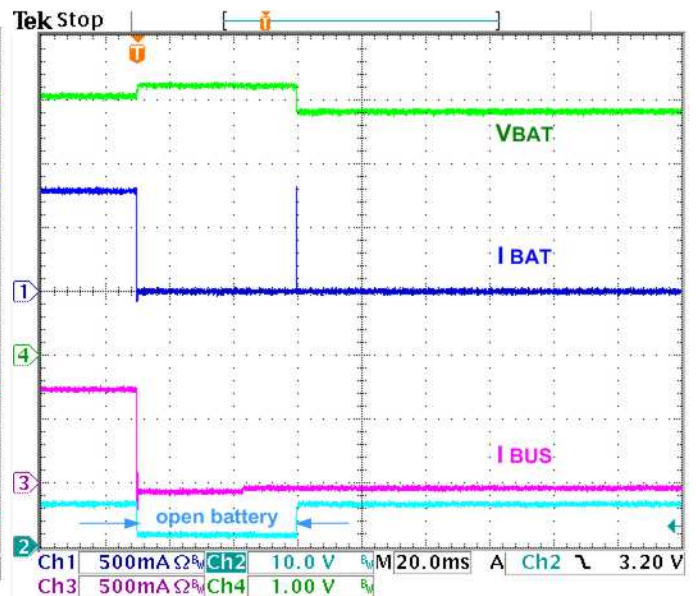


Figure 17. Battery Removal / Insertion during Charging, $V_{BAT}=3.9\text{ V}$, $I_{OCHARGE}=950\text{ mA}$, No I_{INLIM} , $TE=1$

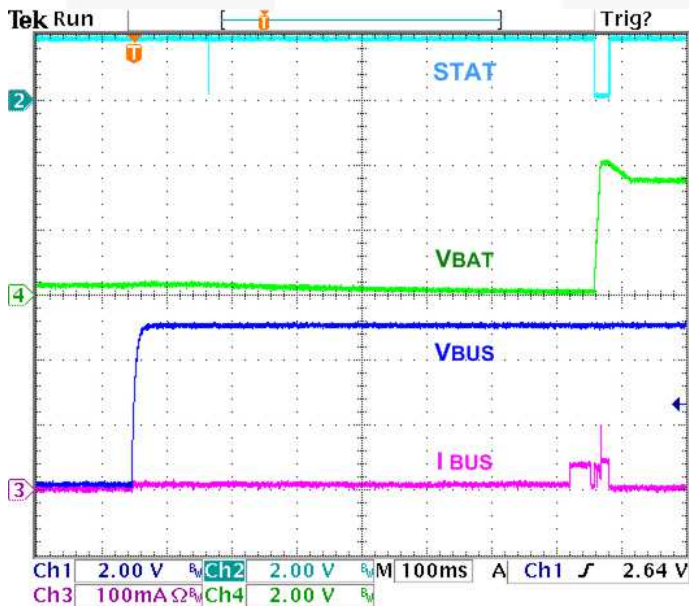


Figure 18. No Battery at V_{BUS} Power-up

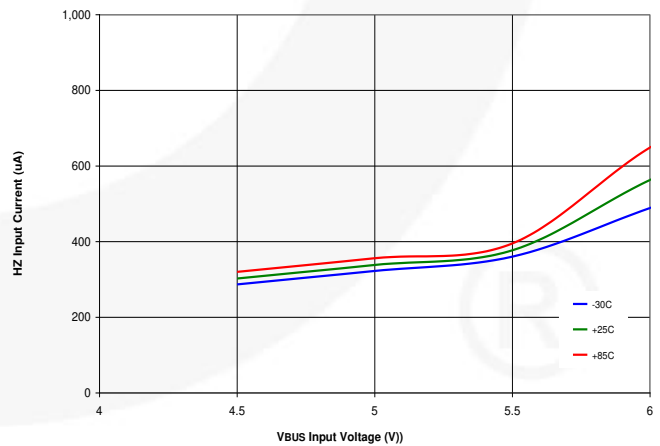


Figure 19. VBUS Current in High-Impedance Mode with Battery Open

VIN Charger Characteristics

Unless otherwise specified, circuit of Figure 1, $V_{OREG} = 4.2\text{ V}$, $V_{IN} = 5.0\text{ V}$, and $T_A = 25^\circ\text{C}$.

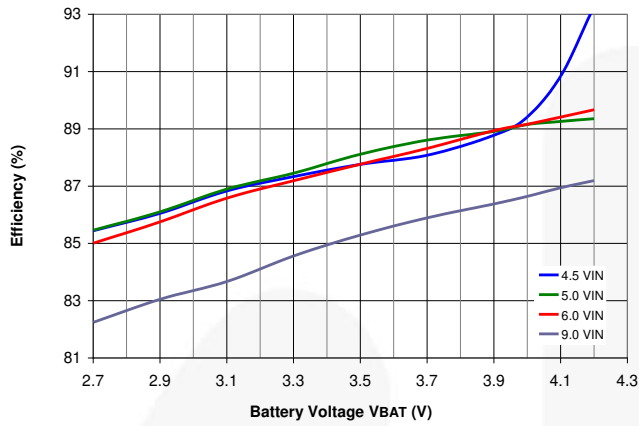


Figure 20. Charger Efficiency, $I_{CHARGE}=950\text{ mA}$

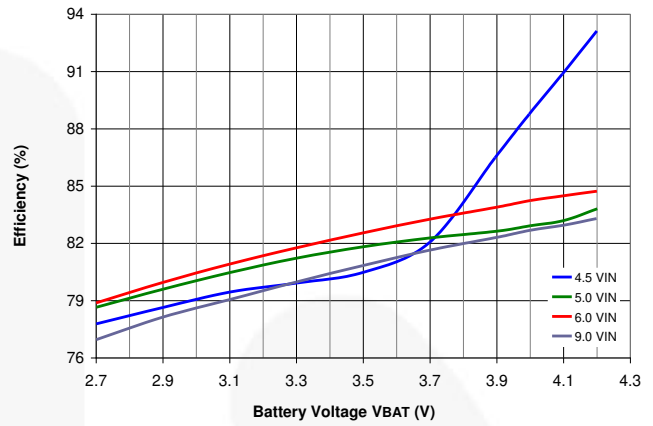


Figure 21. Charger Efficiency, $I_{CHARGE}=1550\text{ mA}$

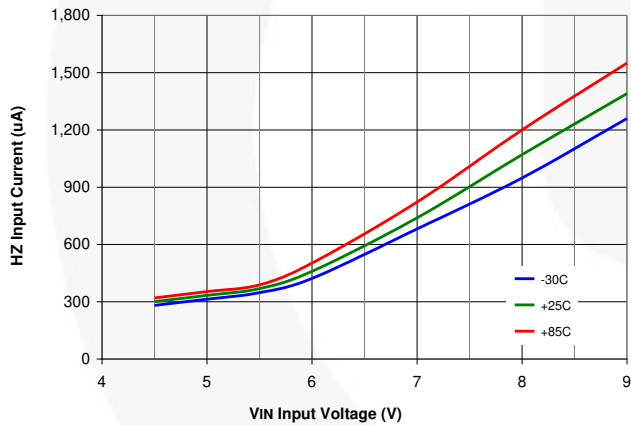


Figure 22. V_{IN} Current in High-Impedance Mode, $V_{BAT}=3.6\text{ V}$

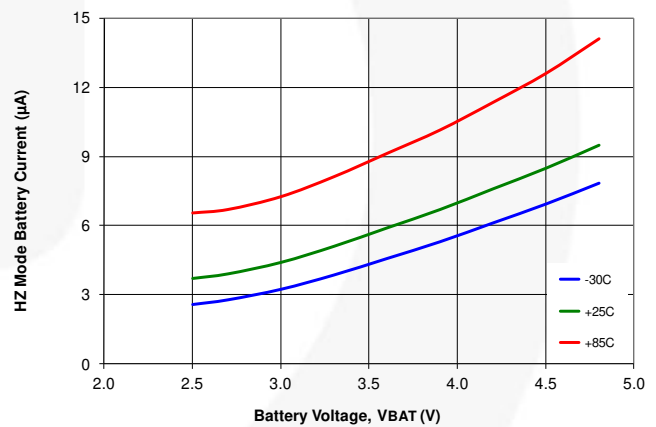


Figure 23. Battery Current in High-Impedance Mode, $V_{BUS}=\text{Open}$, $V_{IN}=\text{Open}$

VIN Charger Characteristics

Unless otherwise specified, circuit of Figure 1, $V_{OREG} = 4.2\text{ V}$, $V_{IN} = 5.0\text{ V}$, and $T_A = 25^\circ\text{C}$.

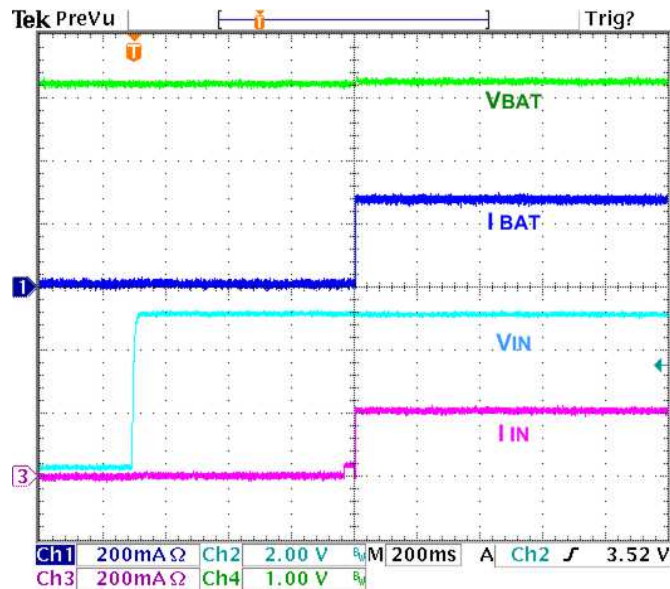


Figure 24. Auto-Charge Startup at V_{IN} Plug-in, $V_{BAT} = 3.2\text{ V}$, $IO_LEVELV = 1$

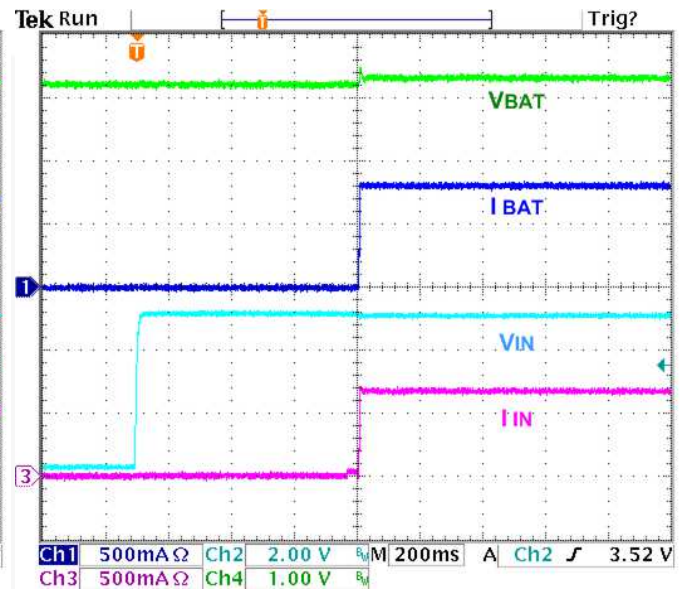


Figure 25. Auto-Charge Startup at V_{IN} Plug-in, $V_{BAT} = 3.2\text{ V}$, $IOCHARGE = 950\text{ mA}$

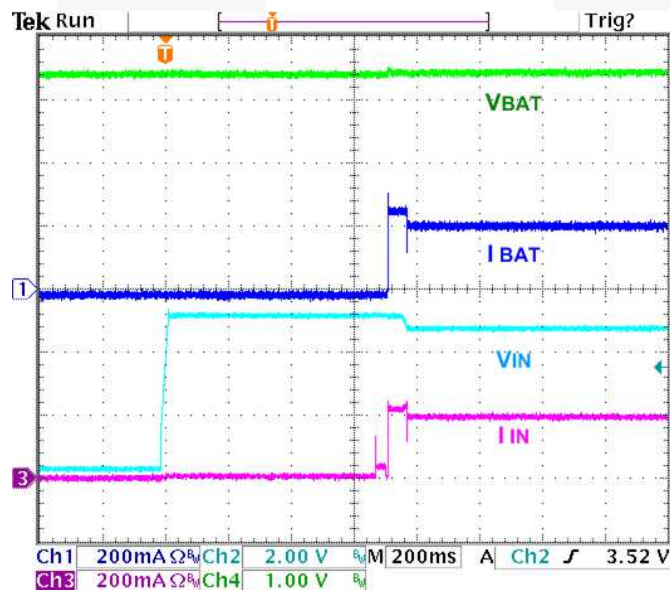


Figure 26. Auto-Charge Startup with 200 mA Limited Charger / Adaptor, $V_{BAT} = 3.4\text{ V}$

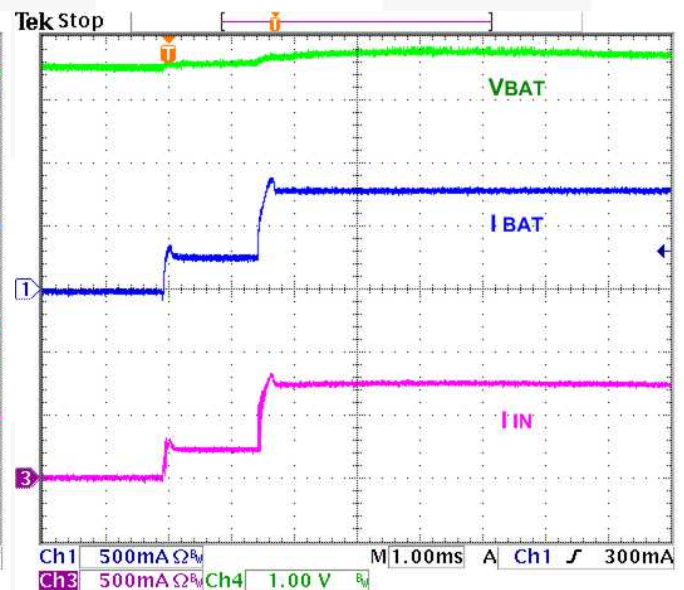


Figure 27. Charger Startup with HZ_MODE Bit Reset, $IOCHARGE = 950\text{ mA}$, $V_{OREG} = 4.2\text{ V}$, $V_{BAT} = 3.6\text{ V}$

VIN Charger Characteristics

Unless otherwise specified, circuit of Figure 1, $V_{OREG} = 4.2\text{ V}$, $V_{IN} = 5.0\text{ V}$, and $T_A = 25^\circ\text{C}$.

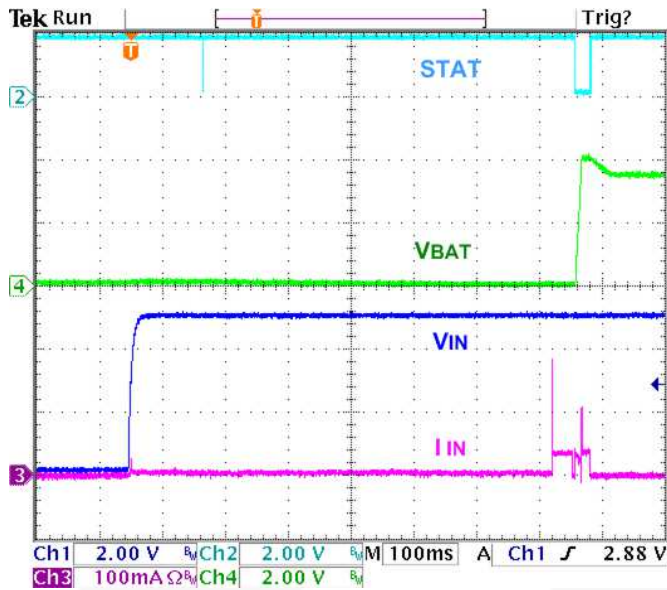


Figure 28. No Battery at V_{IN} Power-up

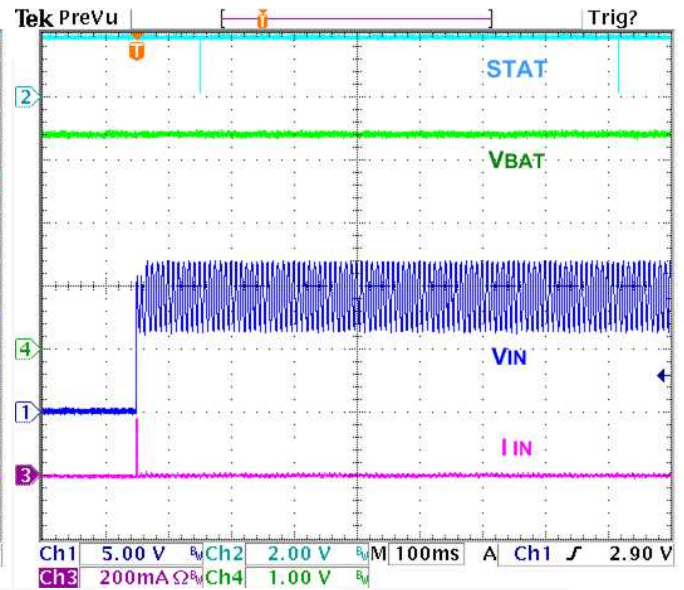


Figure 29. Non-Compliant Charger Rejection, $V_{BAT} = 3.4\text{ V}$

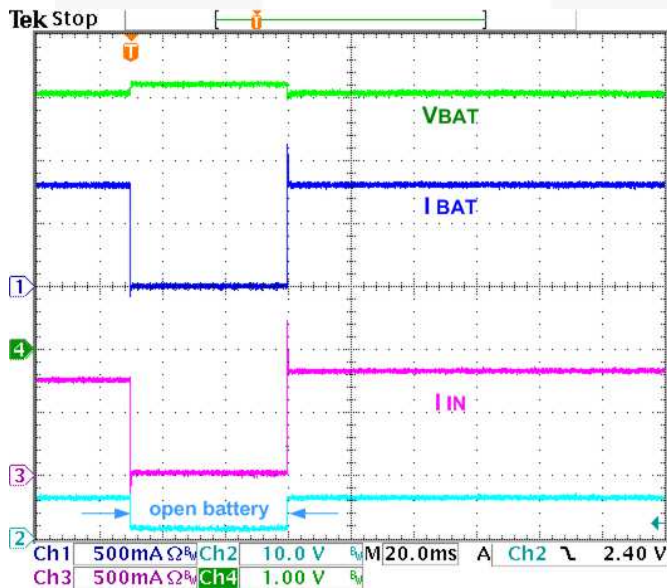


Figure 30. Battery Removal / Insertion During Charging, $V_{BAT} = 3.9\text{ V}$, $I_{CHARGE} = 950\text{ mA}$, $TE = 0$

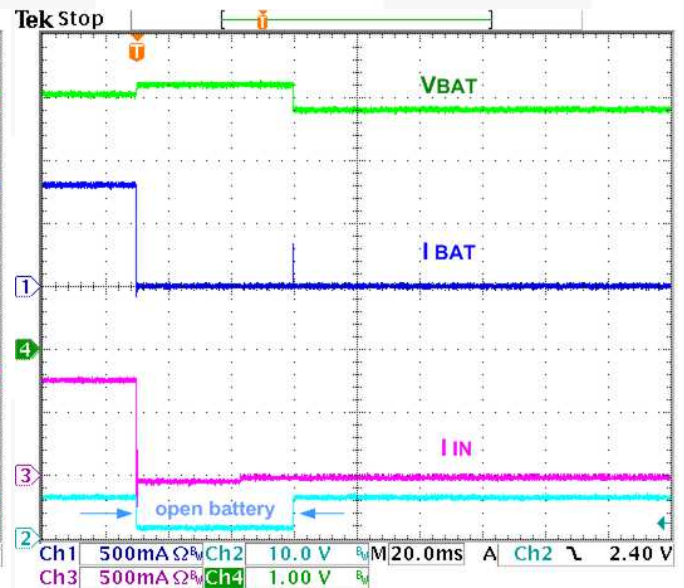


Figure 31. Battery Removal / Insertion During Charging, $V_{BAT} = 3.9\text{ V}$, $I_{CHARGE} = 950\text{ mA}$, $TE = 1$

Boost Mode Typical Characteristics

Unless otherwise specified, using the circuit of Figure 1, $V_{BAT}=3.6\text{ V}$, $T_A=25^\circ\text{C}$.

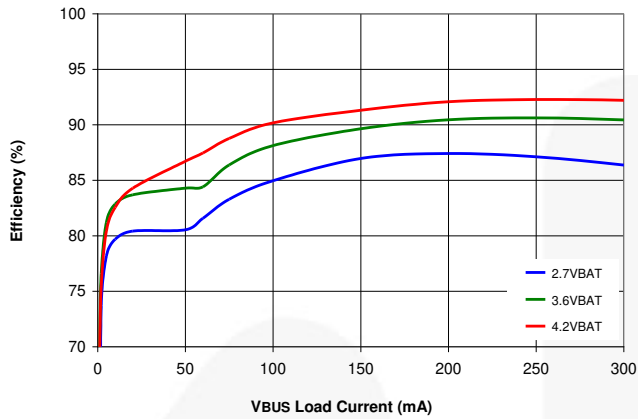


Figure 32. Efficiency vs. V_{BAT}

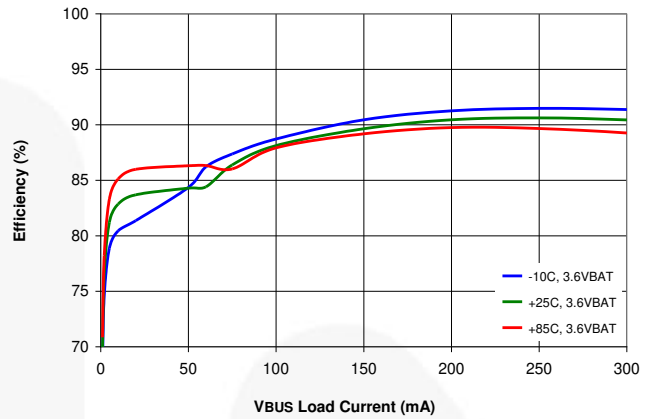


Figure 33. Efficiency Over Temperature

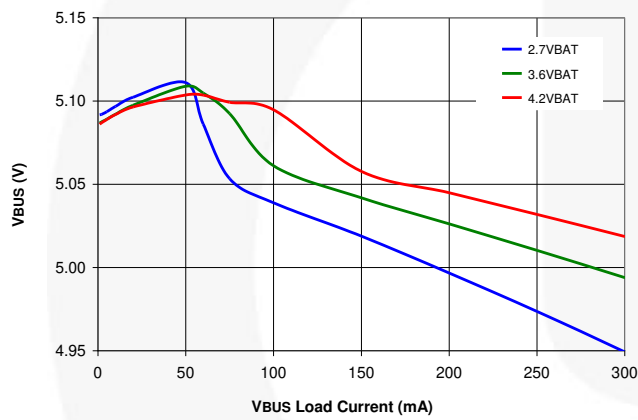


Figure 34. Output Regulation vs. V_{BAT}

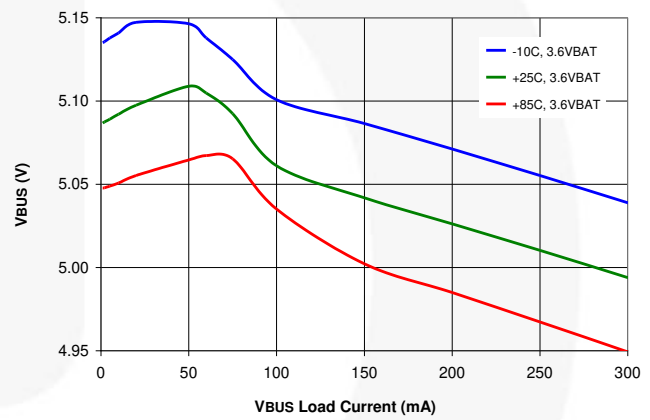


Figure 35. Output Regulation Over Temperature

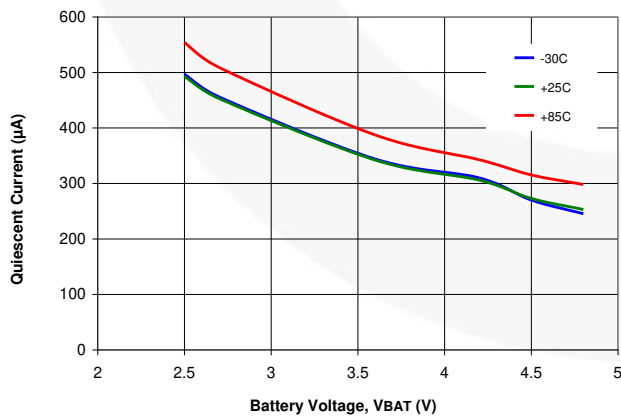


Figure 36. Quiescent Current

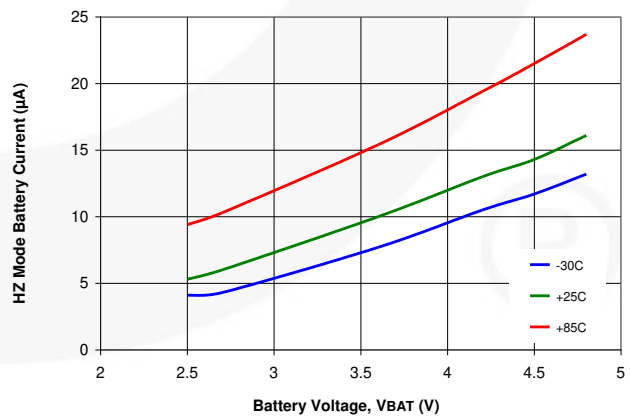


Figure 37. High-Impedance Mode Battery Current

Boost Mode Typical Characteristics

Unless otherwise specified, using the circuit of Figure 1, $V_{BAT}=3.6\text{ V}$, $T_A=25^\circ\text{C}$.

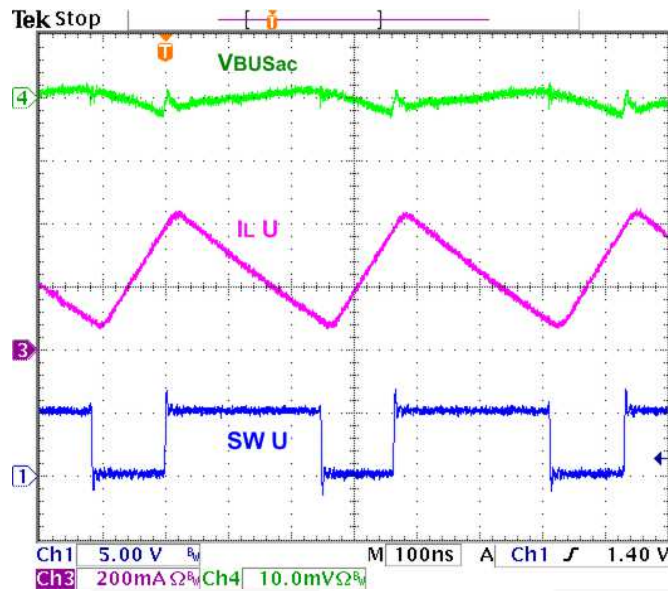


Figure 38. Boost PWM Waveform

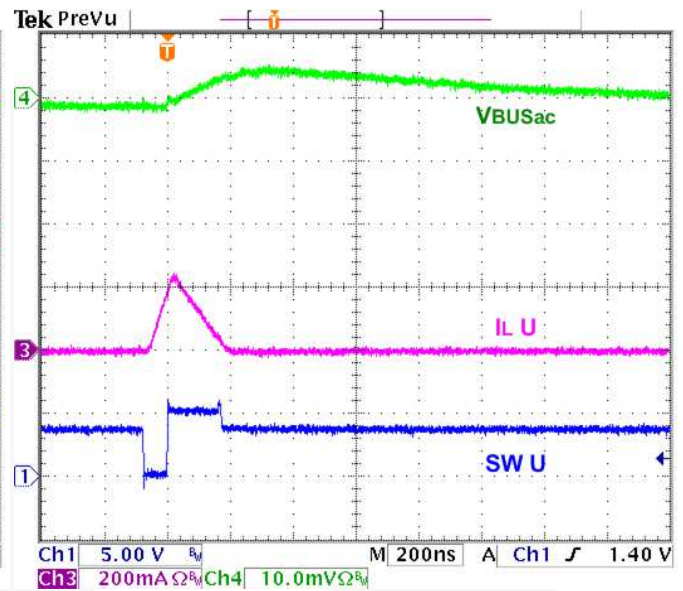


Figure 39. Boost PFM Waveform

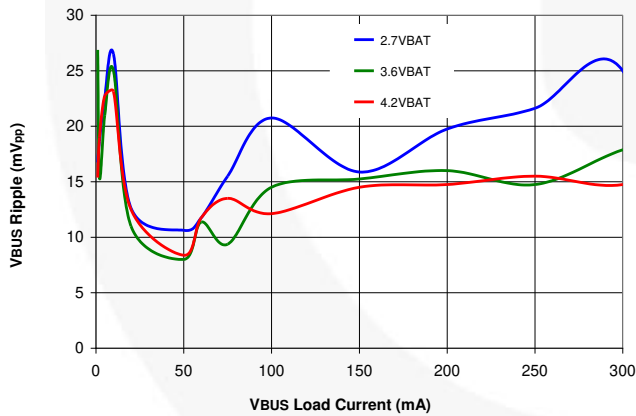


Figure 40. Output Ripple vs. V_{BAT}

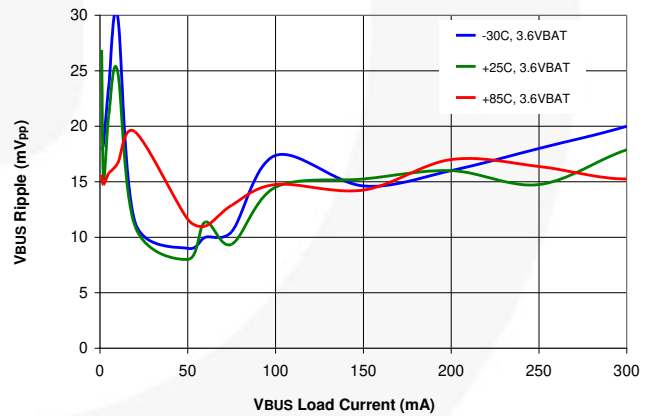


Figure 41. Output Ripple vs. Temperature

Boost Mode Typical Characteristics

Unless otherwise specified, using the circuit of Figure 1, $V_{BAT}=3.6\text{ V}$, $T_A=25^\circ\text{C}$.

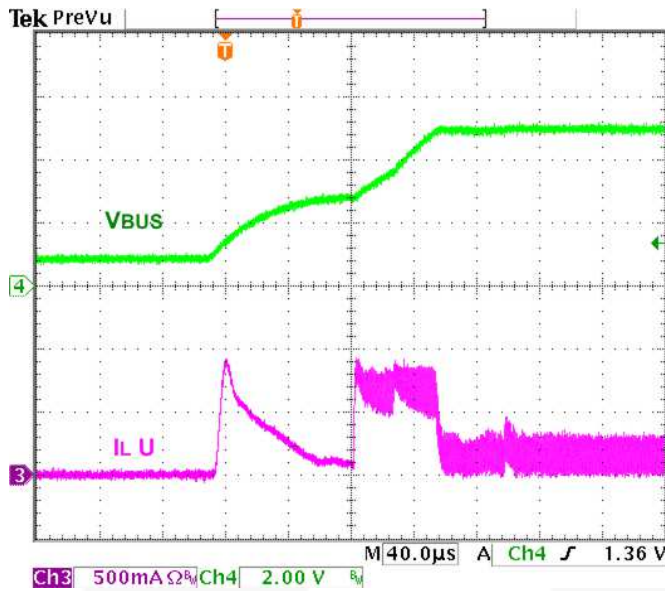


Figure 42. Startup, 3.6 V_{BAT} , 50 Ω Load, Additional 10 μF , X5R Across VBUS

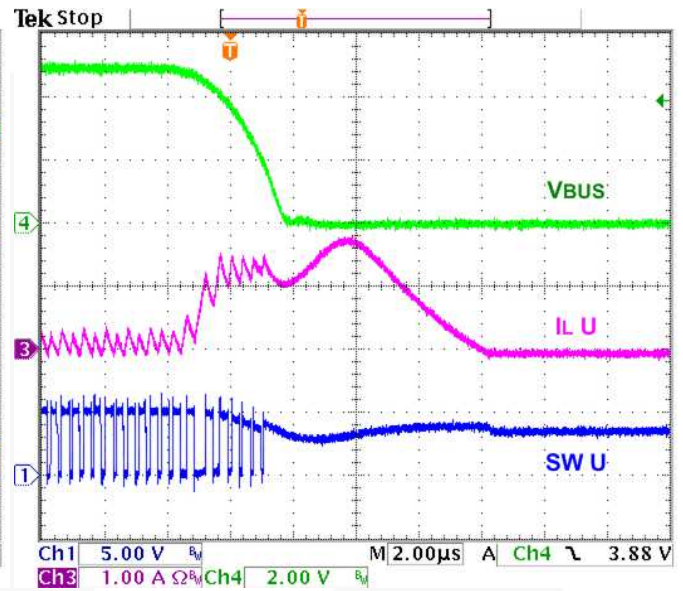


Figure 43. V_{BUS} Fault Response, 3.6 V_{BAT}

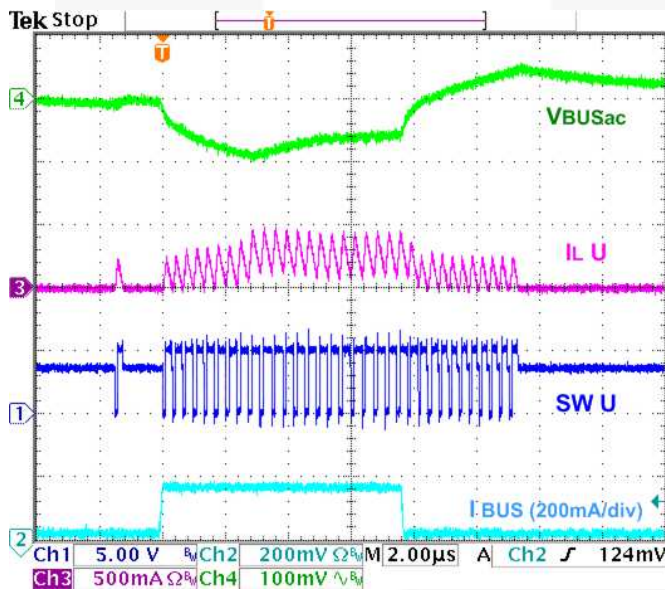


Figure 44. Load Transient, 5-155-5 mA, $t_R=t_F=100\text{ ns}$

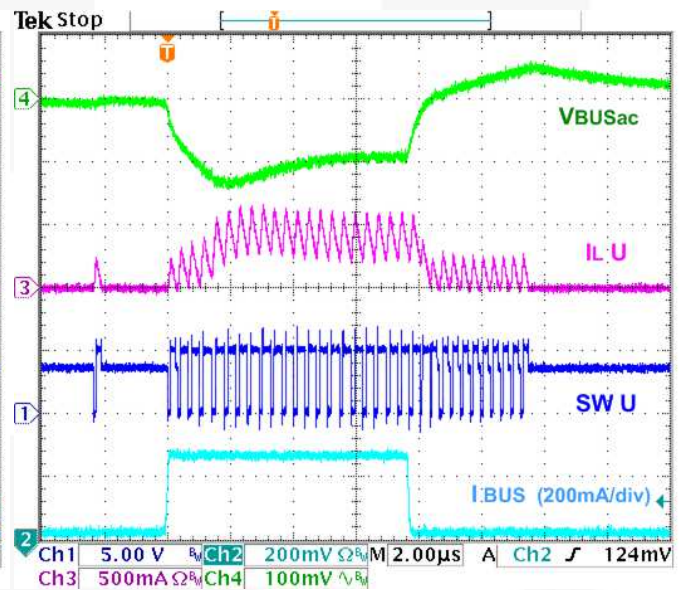


Figure 45. Load Transient, 5-255-5 mA, $t_R=t_F=100\text{ ns}$

Circuit Description / Overview

When charging batteries with a current-limited input source, such as USB, a switching charger's high efficiency over a wide range of output voltages minimizes charging time.

The FAN54300 combines two highly integrated synchronous buck regulators for charging from two separate power sources. The IC also includes a synchronous boost regulator, which can supply 5 V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

In addition to its USB (VBUS) input, the FAN54300 allows a second power source (VIN) to be used for charging. This input source is typically a "wall wart" and can be up to 9.5 V input.

The FAN54300 has three operating modes:

- **Charge Mode:**
Charges a single-cell Li-Ion or Li-polymer battery.
- **Boost Mode:**
Provides 5 V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.
- **High-Impedance Mode:**
Both the boost and charging circuits are off in this mode. Current flow from PWRIN (the charging power source) to the battery, or from the battery to PWRIN, are blocked in this mode. This mode consumes very little current from PWRIN or the battery.

When the IC is charging the battery from VIN, the boost regulator may be simultaneously enabled to supply 5 V for OTG peripherals.

Charge Mode

In Charge Mode, FAN54300 employs five regulation loops:

1. VBUS input current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I²C interface
2. Charging current: Limits the maximum charging current. This current is sensed using an external R_{SENSE} resistor.
3. Charge voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage rises, the battery's internal impedance and R_{SENSE} works in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the voltage across R_{SENSE} drops below the I_{TERM} threshold.
4. Temperature: If the IC's junction temperature reaches 120°C, charge current is continuously reduced until the IC's temperature stabilizes at 120°C.
5. An additional loop limits the amount of drop on VBUS or VIN to a programmable voltage (V_{SP}) to accommodate current-limited wall chargers.

Input Source Selection

The FAN54300 selects the power source (PWRIN) for charging according to the following criteria.

Table 3. PWRIN: Charging Power Input Source Selection

V _{IN}	V _{BUS}	PWRIN
VALID	INVALID	V _{IN}
INVALID	VALID	V _{BUS}
VALID	VALID	V _{IN}

If charging is in progress with V_{BUS} and V_{IN} becomes valid, charging from VBUS stops and charging continues from V_{IN}. Charging stops if HZ_VIN is set when V_{IN} becomes valid while charging with V_{BUS}.

If VIN and VBUS are both connected and t_{15MIN} expires, both CE# bits are set. To reinitiate t_{15MIN} charging (autocharge) with a weak battery, both power sources must be unplugged, then a valid power source plugged in. If only one of the two connected sources are removed then connected with a weak battery, both CE# bits remain set.

Fault Reporting and Register Reset

All faults that occur during charging or boost are reported only in the STATUS register (R0) associated with the active charging source at the time of the fault. Any register reset that occurs due to t_{32SEC} overflow resets only the registers associated with the active charging source.

For example: Assume the IC is charging in 32-Second Mode with V_{IN} as a source. The processor stops setting TMR_RST, so t_{32SEC} expires. The IC then resets only the _V registers and goes into 15-Minute Mode charging with V_{IN}. A timer fault is enunciated, but reported in the CONTROL0_V register. CONTROL0_U is unaffected by this event. When the t_{15MIN} timer expires, the IC sets the CE#_V bit, but leaves the CE#_U bit unchanged.

Battery Charging Curve

If the battery voltage is below V_{SHORT}, a linear current source "pre-charges" the battery until V_{BAT} reaches V_{SHORT}. The PWM charging circuits are then started and the battery is charged with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The FAN54300 is designed to work with a current-limited input source at PWRIN. During the current regulation phase of charging, PWRIN current limitations or the programmed charging current limit the amount of current available to charge the battery and power the system. The effect of input power limitations on I_{CHARGE} can be seen in Figure 47.

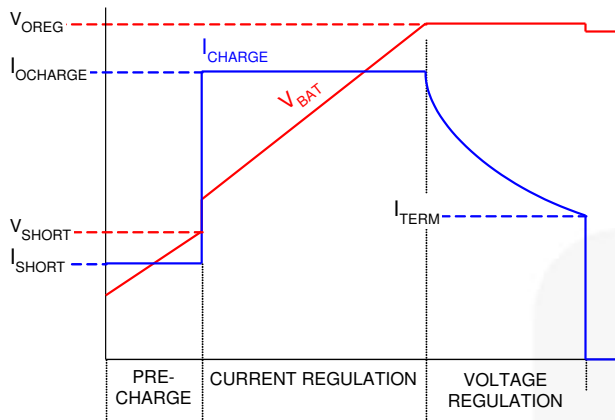


Figure 46. Charge Curve when PWRIN Limitations Don't Limit I_{CHARGE}

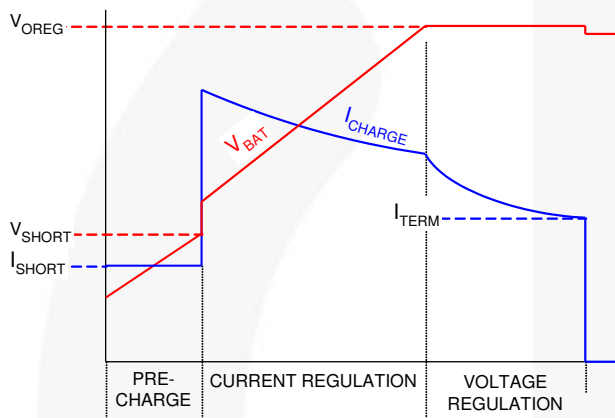


Figure 47. Charge Curve when PWRIN Limits I_{CHARGE}

PWRIN limitations are controlled either by:

- **IBUSLIM:** These bits set the maximum amount of current that the charger draws from V_{BUS} ; OR
- **SP_CHARGER:** For power-limited chargers, the FAN54300 limits current draw when the charging source drops to the voltage programmed by the SP_CHARGER bits. This allows “travel adapters” to be accommodated without host software overhead. The SP_CHARGER control loop applies to both V_{IN} and V_{BUS} .

Assuming V_{OREG} is programmed to the cell's fully charged “float” voltage, the current the battery accepts with the PWM regulator limiting its output (sensed at V_{BAT}) to V_{OREG} declines and the charger enters the voltage regulation phase of charging. When the current declines to the programmed I_{TERM} value, the charge cycle is complete. Charge current termination can be disabled by resetting the TE bit.

Charger Programmability

Throughout this document, any parameter that ends in “U” applies when charging from V_{BUS} and any parameter ending in “V” applies when charging from V_{IN} . Parameters set with slave address D6 are applied when charging from V_{BUS} . Parameters set with slave address D4 are applied when charging from V_{IN} .

The following charging and input power control parameters can be programmed by the host through I^2C .

Table 4. Programmable Charging Parameters

Parameter	Charging Source	Name	Register
Output Voltage Regulation	Either	OREG	REG2[7:2]
Battery Charging Current Limit	V_{BUS}	ICHGU	REG4[6:4]
	V_{IN}	ICHGV	REG4[6:3]
Input Current Limit	V_{BUS}	IBUSLIM	REG1[7:6]
Charge Termination Limit	Either	ITERM	REG4[2:0]
Special Charger Minimum Voltage	Either	VSP	REG5[2:0]

The charger output or “float” voltage can be programmed by the OREG bits from 3.5 V to 4.44 V in 20 mV increments.

Table 5. OREG Bits (REG2 [7:2]) vs. Charger V_{OUT} (V_{OREG}) Float Voltage

Decimal	Hex	VOREG	Decimal	Hex	VOREG
0	00	3.50	32	20	4.14
1	01	3.52	33	21	4.16
2	02	3.54	34	22	4.18
3	03	3.56	35	23	4.20
4	04	3.58	36	24	4.22
5	05	3.60	37	25	4.24
6	06	3.62	38	26	4.26
7	07	3.64	39	27	4.28
8	08	3.66	40	28	4.30
9	09	3.68	41	29	4.32
10	0A	3.70	42	2A	4.34
11	0B	3.72	43	2B	4.36
12	0C	3.74	44	2C	4.38
13	0D	3.76	45	2D	4.40
14	0E	3.78	46	2E	4.42
15	0F	3.80	47	2F	4.44
16	10	3.82	48	30	4.44
17	11	3.84	49	31	4.44
18	12	3.86	50	32	4.44
19	13	3.88	51	33	4.44
20	14	3.90	52	34	4.44
21	15	3.92	53	35	4.44
22	16	3.94	54	36	4.44
23	17	3.96	55	37	4.44
24	18	3.98	56	38	4.44
25	19	4.00	57	39	4.44
26	1A	4.02	58	3A	4.44
27	1B	4.04	59	3B	4.44
28	1C	4.06	60	3C	4.44
29	1D	4.08	61	3D	4.44
30	1E	4.10	62	3E	4.44
31	1F	4.12	63	3F	4.44

Note:

- All register default settings are noted by **bold typeface**.